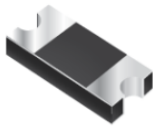
MATERIAL DECLARATION SHEET

BOURNS®

Material Number	**CD214A-FS1x**		
Product Line	**Semiconductor Products**		
Compliance Date	**2019/8/2**		
RoHS Compliant	**Yes**	**MSL**	**1**



No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Metal	12.01	Continuous filament glass fibers	65997-17-3	25.10%	15.072550%	60.05%
				Phosphorus-based epoxy resin	Confidentiality	23.11%	13.877555%	
				Inorganic filler	Confidentiality	12.07%	7.248035%	
				Copper	7440-50-8	39.45%	23.689725%	
				Zinc	7440-66-6	0.20%	0.120100%	
				Nickel	7440-02-0	0.05%	0.030025%	
				Chromium	7440-47-3	0.01%	0.006005%	
				Arsenic	7440-38-2	0.01%	0.006005%	
2	Epoxy	Plastic	4.23	Silicon Dioxide	7631-86-9	57.14%	12.085110%	21.15%
				Bis-Phenol Type Epoxy	9003-36-5	42.86%	9.064890%	
3	Die Attach	Metal	0.25	Lead (Note 2)	7439-92-1	92.5%	1.156250%	1.25%
				Tin	7440-31-5	5.0%	0.062500%	
				Silver	7440-22-4	2.5%	0.031250%	
4	Dice	Others	3.11	Silicon	7440-21-3	73.54%	11.4354690%	15.55%
				Nickel	7440-02-0	1.99%	0.3094450%	
				Aluminum	7429-90-5	0.56%	0.0870800%	
				Lead Glass (Note 3)	7439-92-1	14.80%	2.3014000%	
				Phosphorus	7723-14-0	0.249%	0.0387200%	
				Boron	7440-42-8	0.874%	0.1359070%	
				Misc not to declare	Confidentiality	7.987%	1.2419790%	
5	Terminal Plating	Metal	0.4	Tin	7440-31-5	100%	2.000000%	2.00%
		Total weight	20					

This Document was updated on: 2019/8/2

Important remarks:

1. **It is the responsibility of the user to verify they are accessing the latest version.**
2. **RoHS exemption 7(a): Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)**
3. **RoHS exemption 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezo-electronic devices, or in a glass or ceramic matrix compound**